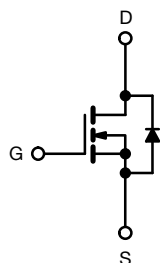
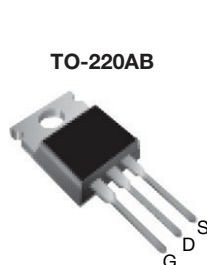


## E Series Power MOSFET With Fast Body Diode and Low Gate Charge



N-Channel MOSFET

### FEATURES

- Reduced figure-of-merit (FOM):  $R_{on} \times Q_g$
- Fast body diode MOSFET using E series technology
- Reduced  $t_{rr}$ ,  $Q_{rr}$ , and  $I_{RRM}$
- Increased robustness due to low  $Q_{rr}$
- Low input capacitance ( $C_{iss}$ )
- Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
**HALOGEN**  
**FREE**  
Available

### PRODUCT SUMMARY

|                                         |                 |       |
|-----------------------------------------|-----------------|-------|
| $V_{DS}$ (V) at $T_J$ max.              | 650             |       |
| $R_{DS(on)}$ typ. ( $\Omega$ ) at 25 °C | $V_{GS} = 10$ V | 0.127 |
| $Q_g$ (Max.) (nC)                       | 75              |       |
| $Q_{gs}$ (nC)                           | 17              |       |
| $Q_{gd}$ (nC)                           | 19              |       |
| Configuration                           | Single          |       |

### APPLICATIONS

- Telecommunications
  - Server and telecom power supplies
- Computing
  - ATX power supplies
- Industrial
  - Welding
  - Induction heating
  - Battery chargers
  - Uninterruptible power supplies (UPS)
- Renewable energy
  - String PV inverters

### ORDERING INFORMATION

|                                 |                                                   |
|---------------------------------|---------------------------------------------------|
| Package                         | TO-220AB                                          |
| Lead (Pb)-free and halogen-free | SiHP25N60EFL-BE3 <sup>a</sup><br>SiHP25N60EFL-GE3 |

#### Note

a. "-BE3" denotes alternate manufacturing location

### ABSOLUTE MAXIMUM RATINGS ( $T_C = 25$ °C, unless otherwise noted)

| PARAMETER                                                 | SYMBOL           | LIMIT          | UNIT |
|-----------------------------------------------------------|------------------|----------------|------|
| Drain-source voltage                                      | $V_{DS}$         | 600            | V    |
| Gate-source voltage                                       | $V_{GS}$         | $\pm 30$       |      |
| Continuous drain current ( $T_J = 150$ °C)                | $V_{GS}$ at 10 V | $T_C = 25$ °C  | A    |
|                                                           |                  | $T_C = 100$ °C |      |
| Pulsed drain current <sup>a</sup>                         | $I_{DM}$         | 61             |      |
| Linear derating factor                                    |                  | 2              | W/°C |
| Single pulse avalanche energy <sup>b</sup>                | $E_{AS}$         | 353            | mJ   |
| Maximum power dissipation                                 | $P_D$            | 250            | W    |
| Operating junction and storage temperature range          | $T_J, T_{stg}$   | -55 to +150    | °C   |
| Drain-source voltage slope                                | $dV/dt$          | $T_J = 125$ °C | V/ns |
| Reverse diode $dV/dt$ <sup>d</sup>                        |                  |                |      |
| Soldering recommendations (peak temperature) <sup>c</sup> |                  | For 10 s       | °C   |

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature  
 b.  $V_{DD} = 140$  V, starting  $T_J = 25$  °C,  $L = 28.2$  mH,  $R_g = 25$   $\Omega$ ,  $I_{AS} = 5$  A  
 c. 1.6 mm from case



d.  $I_{SD} \leq I_D$ ,  $dI/dt = 100 \text{ A}/\mu\text{s}$ , starting  $T_J = 25^\circ\text{C}$

### THERMAL RESISTANCE RATINGS

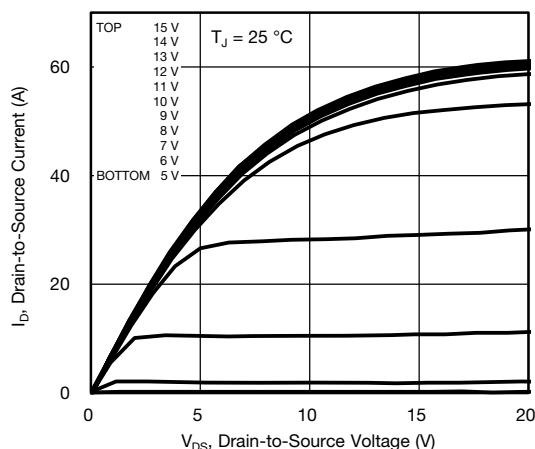
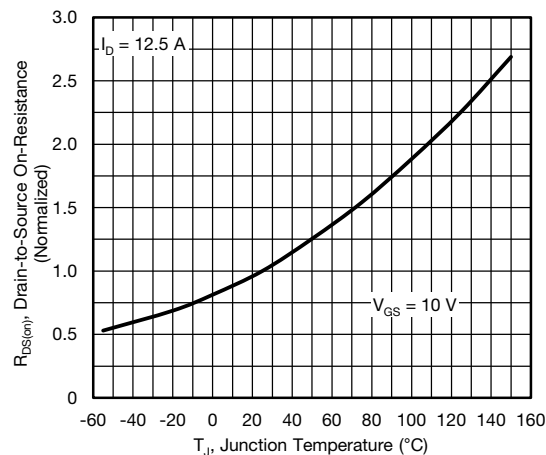
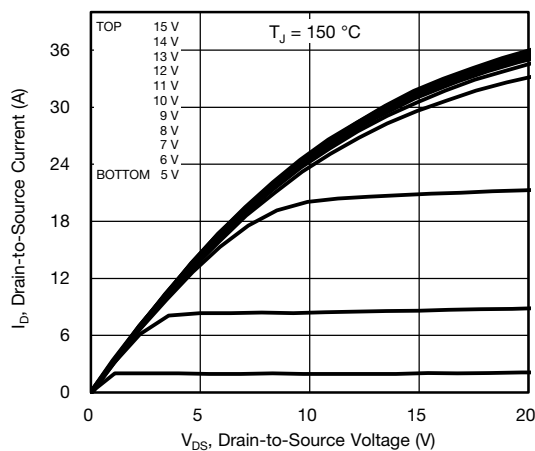
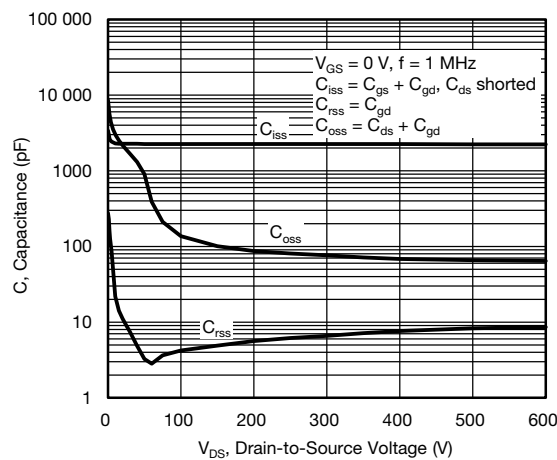
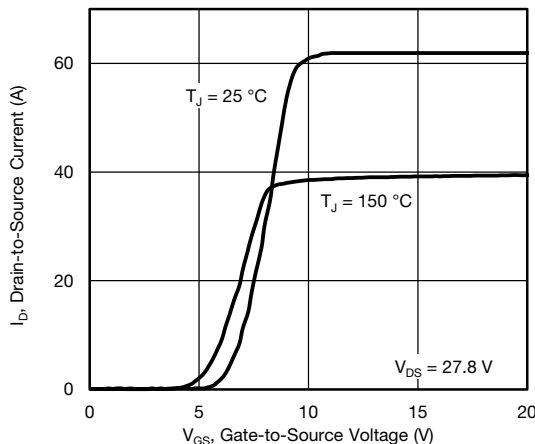
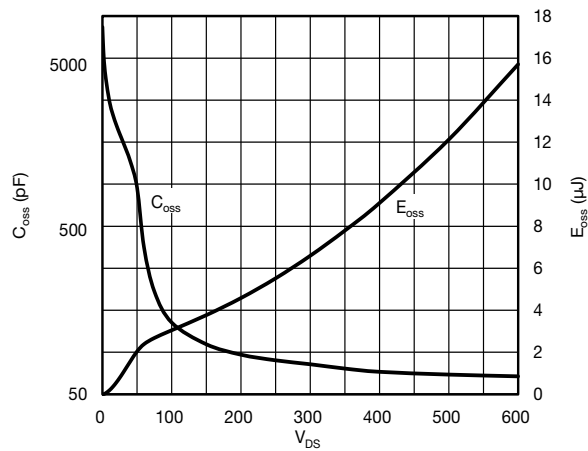
| PARAMETER                        | SYMBOL     | TYP. | MAX. | UNIT                      |
|----------------------------------|------------|------|------|---------------------------|
| Maximum junction-to-ambient      | $R_{thJA}$ | -    | 62   | $^\circ\text{C}/\text{W}$ |
| Maximum junction-to-case (drain) | $R_{thJC}$ | -    | 0.5  |                           |

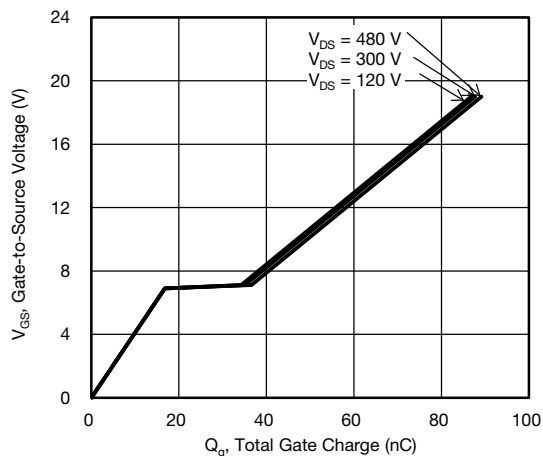
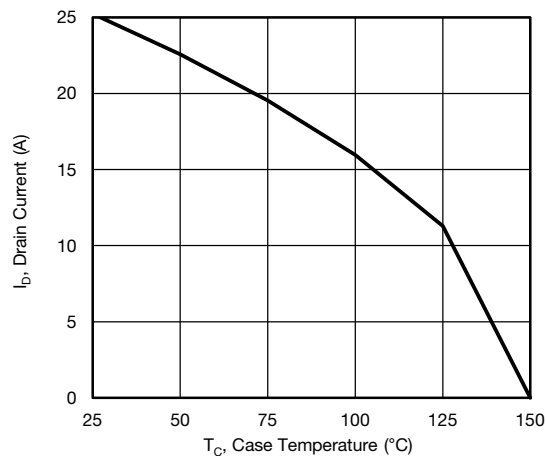
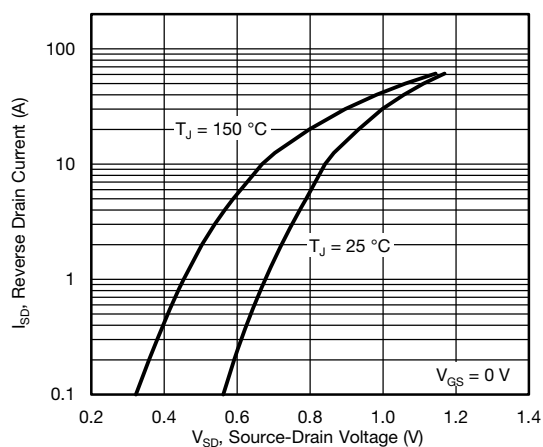
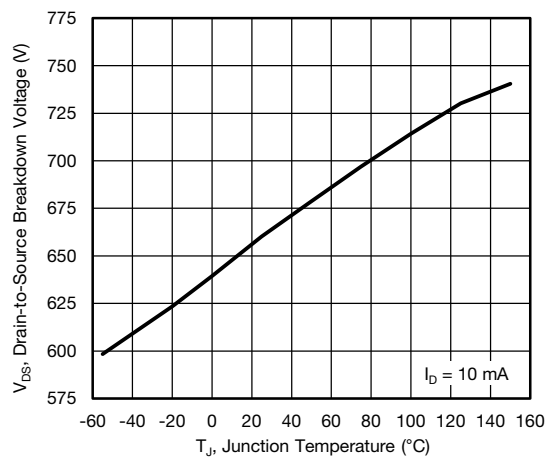
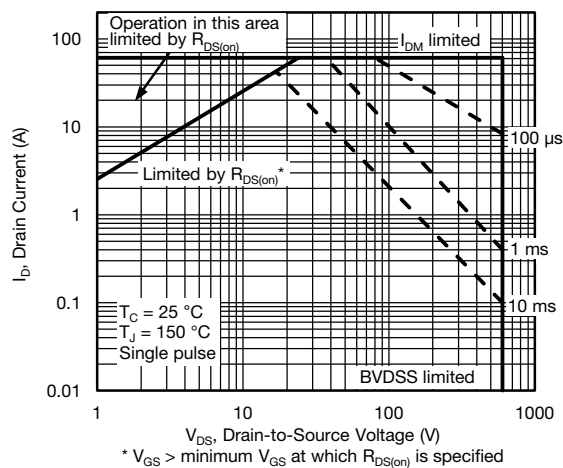
### SPECIFICATIONS ( $T_J = 25^\circ\text{C}$ , unless otherwise noted)

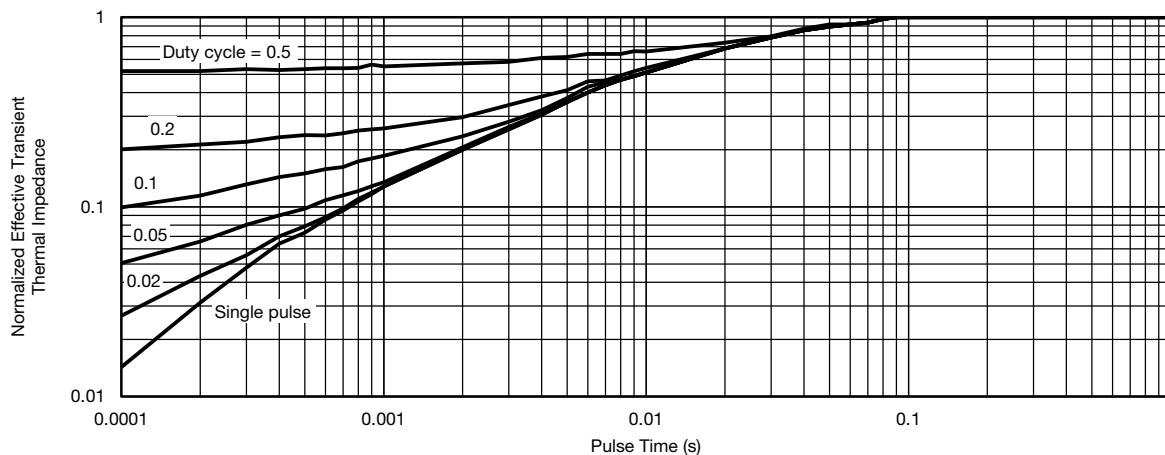
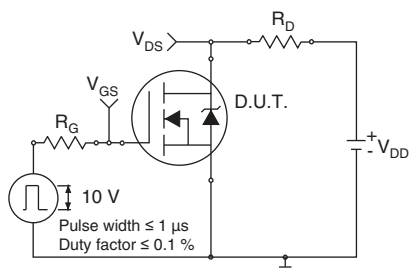
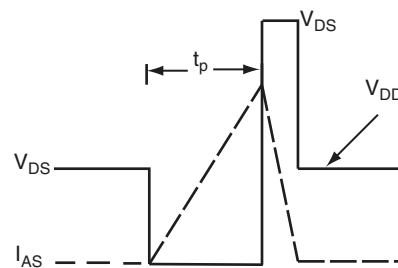
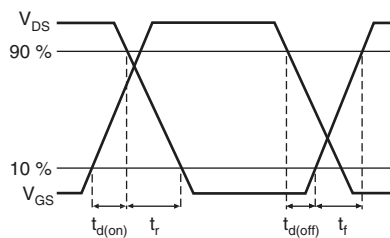
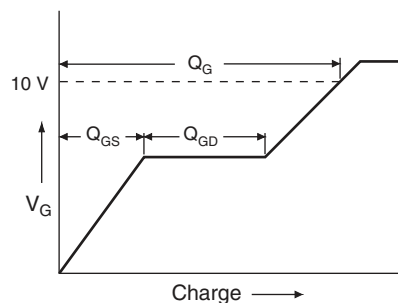
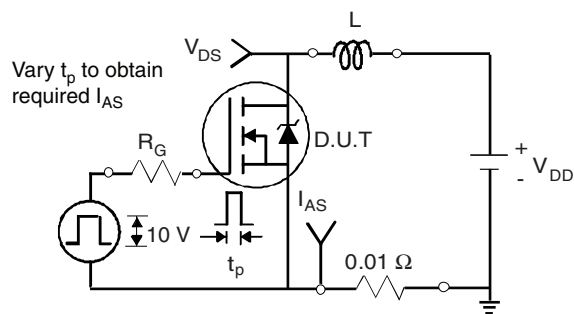
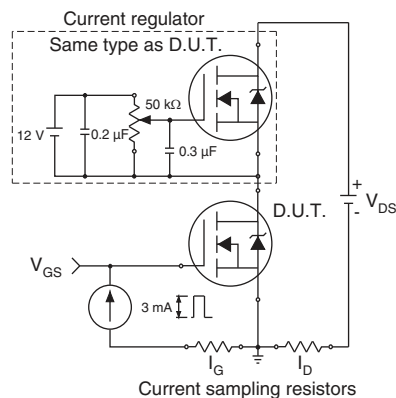
| PARAMETER                                                 | SYMBOL              | TEST CONDITIONS                                                                                                                                       | MIN. | TYP.  | MAX.      | UNIT                      |
|-----------------------------------------------------------|---------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------|------|-------|-----------|---------------------------|
| <b>Static</b>                                             |                     |                                                                                                                                                       |      |       |           |                           |
| Drain-source breakdown voltage                            | $V_{DS}$            | $V_{GS} = 0 \text{ V}$ , $I_D = 250 \mu\text{A}$                                                                                                      | 600  | -     | -         | V                         |
| $V_{DS}$ temperature coefficient                          | $\Delta V_{DS}/T_J$ | Reference to $25^\circ\text{C}$ , $I_D = 10 \text{ mA}$                                                                                               | -    | 0.69  | -         | $\text{V}/^\circ\text{C}$ |
| Gate-source threshold Voltage (N)                         | $V_{GS(th)}$        | $V_{DS} = V_{GS}$ , $I_D = 250 \mu\text{A}$                                                                                                           | 3.0  | -     | 5.0       | V                         |
| Gate-source leakage                                       | $I_{GSS}$           | $V_{GS} = \pm 20 \text{ V}$                                                                                                                           | -    | -     | $\pm 100$ | nA                        |
|                                                           |                     | $V_{GS} = \pm 30 \text{ V}$                                                                                                                           | -    | -     | $\pm 1$   | $\mu\text{A}$             |
| Zero gate voltage drain current                           | $I_{DSS}$           | $V_{DS} = 480 \text{ V}$ , $V_{GS} = 0 \text{ V}$                                                                                                     | -    | -     | 1         | $\mu\text{A}$             |
|                                                           |                     | $V_{DS} = 480 \text{ V}$ , $V_{GS} = 0 \text{ V}$ , $T_J = 125^\circ\text{C}$                                                                         | -    | -     | 500       |                           |
| Drain-source on-state resistance                          | $R_{DS(on)}$        | $V_{GS} = 10 \text{ V}$ , $I_D = 12.5 \text{ A}$                                                                                                      | -    | 0.127 | 0.146     | $\Omega$                  |
| Forward transconductance                                  | $g_{fs}$            | $V_{DS} = 30 \text{ V}$ , $I_D = 12.5 \text{ A}$                                                                                                      | -    | 11.3  | -         | S                         |
| <b>Dynamic</b>                                            |                     |                                                                                                                                                       |      |       |           |                           |
| Input capacitance                                         | $C_{iss}$           | $V_{GS} = 0 \text{ V}$ ,<br>$V_{DS} = 100 \text{ V}$ ,<br>$f = 1 \text{ MHz}$                                                                         | -    | 2274  | -         | pF                        |
| Output capacitance                                        | $C_{oss}$           |                                                                                                                                                       | -    | 137   | -         |                           |
| Reverse transfer capacitance                              | $C_{rss}$           |                                                                                                                                                       | -    | 4     | -         |                           |
| Effective output capacitance, energy related <sup>a</sup> | $C_{o(er)}$         | $V_{DS} = 0 \text{ V to } 480 \text{ V}$ , $V_{GS} = 0 \text{ V}$                                                                                     | -    | 79    | -         |                           |
| Effective output capacitance, time related <sup>b</sup>   | $C_{o(tr)}$         |                                                                                                                                                       | -    | 330   | -         |                           |
| Total gate charge                                         | $Q_g$               | $V_{GS} = 10 \text{ V}$ , $I_D = 12.5 \text{ A}$ , $V_{DS} = 480 \text{ V}$                                                                           | -    | 50    | 75        | nC                        |
| Gate-source charge                                        | $Q_{gs}$            |                                                                                                                                                       | -    | 17    | -         |                           |
| Gate-drain charge                                         | $Q_{gd}$            |                                                                                                                                                       | -    | 19    | -         |                           |
| Turn-on delay time                                        | $t_{d(on)}$         | $V_{DD} = 480 \text{ V}$ , $I_D = 12.5 \text{ A}$ ,<br>$R_g = 9.1 \Omega$ , $V_{GS} = 10 \text{ V}$                                                   | -    | 25    | 50        | ns                        |
| Rise time                                                 | $t_r$               |                                                                                                                                                       | -    | 39    | 68        |                           |
| Turn-off delay time                                       | $t_{d(off)}$        |                                                                                                                                                       | -    | 47    | 94        |                           |
| Fall time                                                 | $t_f$               |                                                                                                                                                       | -    | 21    | 42        |                           |
| Gate input resistance                                     | $R_g$               | $f = 1 \text{ MHz}$ , open drain                                                                                                                      | 0.4  | 0.7   | 1.4       | $\Omega$                  |
| <b>Drain-Source Body Diode Characteristics</b>            |                     |                                                                                                                                                       |      |       |           |                           |
| Continuous source-drain diode current                     | $I_S$               | MOSFET symbol showing the integral reverse p - n junction diode  | -    | -     | 25        | A                         |
| Pulsed diode forward current                              | $I_{SM}$            |                                                                                                                                                       | -    | -     | 61        |                           |
| Diode forward voltage                                     | $V_{SD}$            | $T_J = 25^\circ\text{C}$ , $I_S = 12.5 \text{ A}$ , $V_{GS} = 0 \text{ V}$                                                                            | -    | 0.9   | 1.2       | V                         |
| Reverse recovery time                                     | $t_{rr}$            | $T_J = 25^\circ\text{C}$ , $I_F = I_S = 12.5 \text{ A}$ ,<br>$dI/dt = 100 \text{ A}/\mu\text{s}$ , $V_R = 25 \text{ V}$                               | -    | 138   | 276       | ns                        |
| Reverse recovery charge                                   | $Q_{rr}$            |                                                                                                                                                       | -    | 0.8   | 1.6       | $\mu\text{C}$             |
| Reverse recovery current                                  | $I_{RRM}$           |                                                                                                                                                       | -    | 11    | -         | A                         |

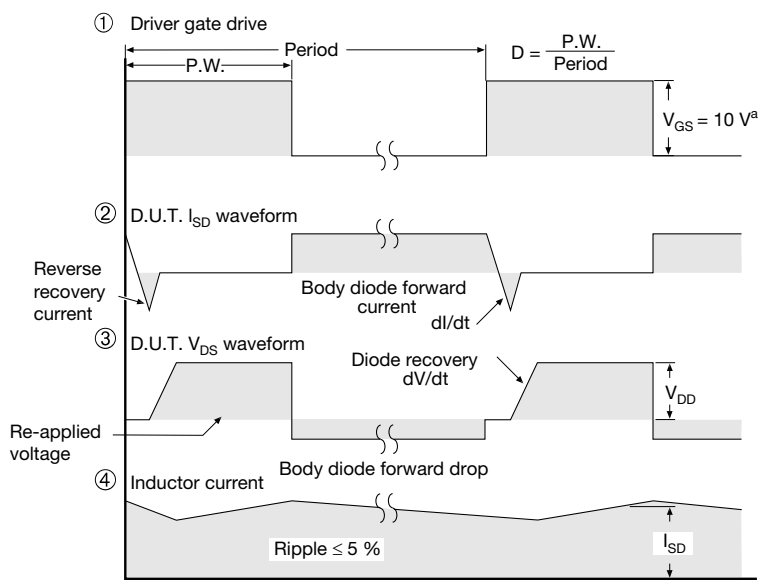
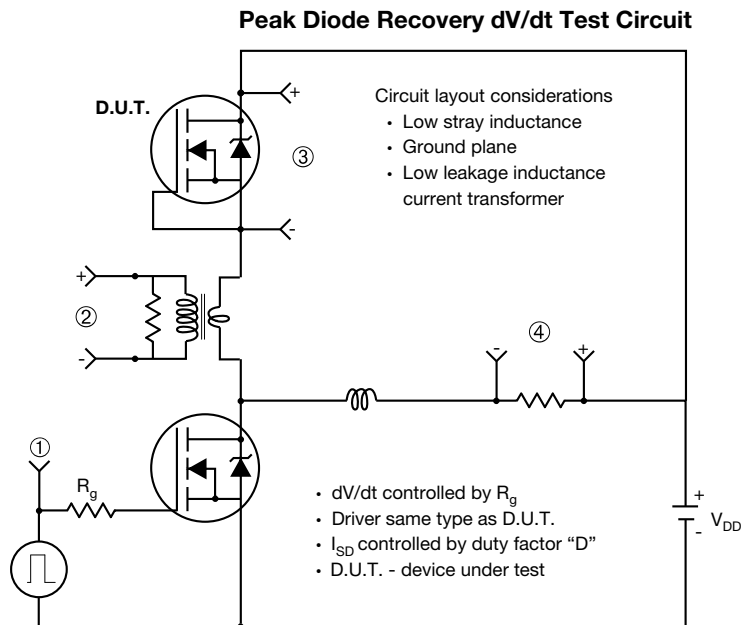
#### Notes

- a.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$   
b.  $C_{oss(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DSS}$

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

**Fig. 1 - Typical Output Characteristics**

**Fig. 4 - Normalized On-Resistance vs. Temperature**

**Fig. 2 - Typical Output Characteristics**

**Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage**

**Fig. 3 - Typical Transfer Characteristics**

**Fig. 6 -  $C_{oss}$  and  $E_{oss}$  vs.  $V_{DS}$**


**Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage**

**Fig. 10 - Maximum Drain Current vs. Case Temperature**

**Fig. 8 - Typical Source-Drain Diode Forward Voltage**

**Fig. 11 - Typical Drain-to-Source Voltage vs. Temperature**

**Fig. 9 - Maximum Safe Operating Area**


**Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case**

**Fig. 13 - Switching Time Test Circuit**

**Fig. 16 - Unclamped Inductive Waveforms**

**Fig. 14 - Switching Time Waveforms**

**Fig. 17 - Basic Gate Charge Waveform**

**Fig. 15 - Unclamped Inductive Test Circuit**

**Fig. 18 - Gate Charge Test Circuit**



**Fig. 19 - For N-Channel**

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